NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.0203 ± 0.001
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QP TECHNOLOGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
   250 TO 300 MICRONICHES (10um-12.5um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
   (30 TO 50 MICRONICHES (1um-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
ANGULAR: ±0.5 degree
.X = ±0.40
.XX = ±0.25
.XXX = ±0.13
.XXXX = ±0.01

MATERIAL
SEE NOTE 1
FINISH
SEE NOTE 2
COMMENTS

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